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(54) Title: PROCESS FOR FABRICATING A HERMETIC GLASS-TO-METAL SEAL		
(57) Abstract		
A process for forming a hermetic glass-to-metal seal between a conductive pin (16) and an outer body (12), wherein a corrosion-resistant noble metal (e.g., gold) coating is applied to the conductive pin (16) before the hermetic seal is formed. The process generally includes providing a noble metal-coated conductive pin (16), placing glass (14) having a softening point less than about 650 °C into a cavity (18) of the outer body (12), inserting the coated conductive pin (16) into a bore (20) in the glass preform (14), heating the assembly to a temperature in excess of the softening point of the glass but less than about 700 °C and cooling the assembly. The coefficients of thermal expansion of the components of the assembly are preferably selected such that the resulting assembly is a hermetic compression seal.		